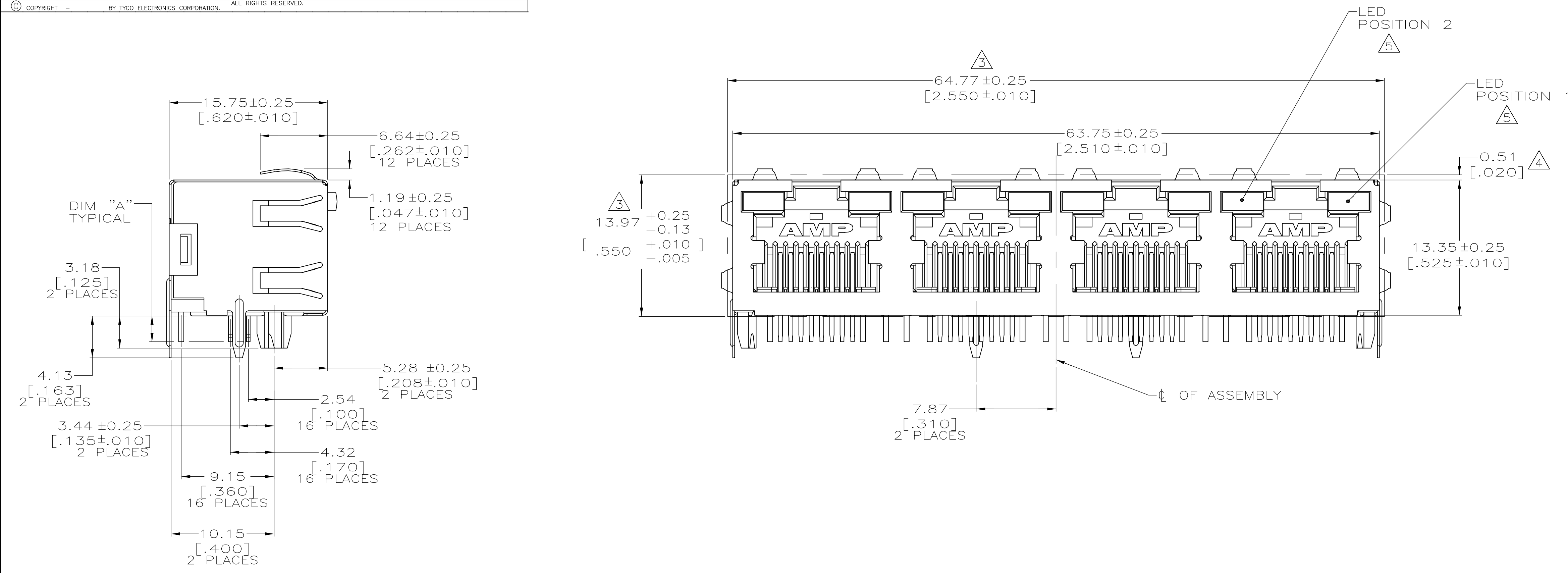
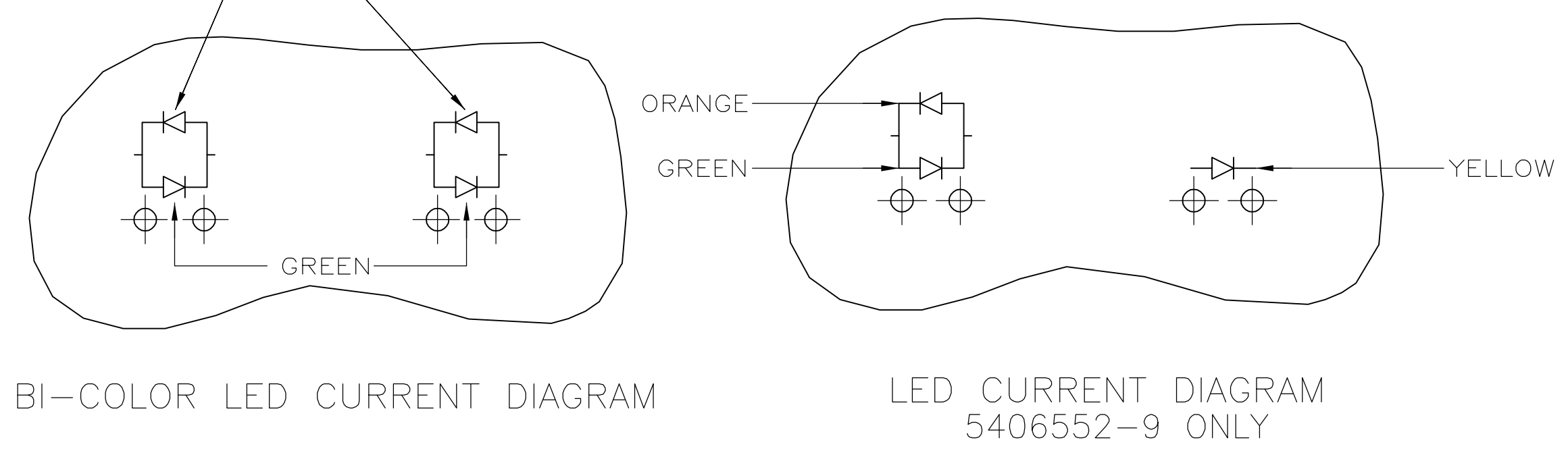


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	APP'D		
D	ECO-06-013742		09JUNE2006	LAM	JW		



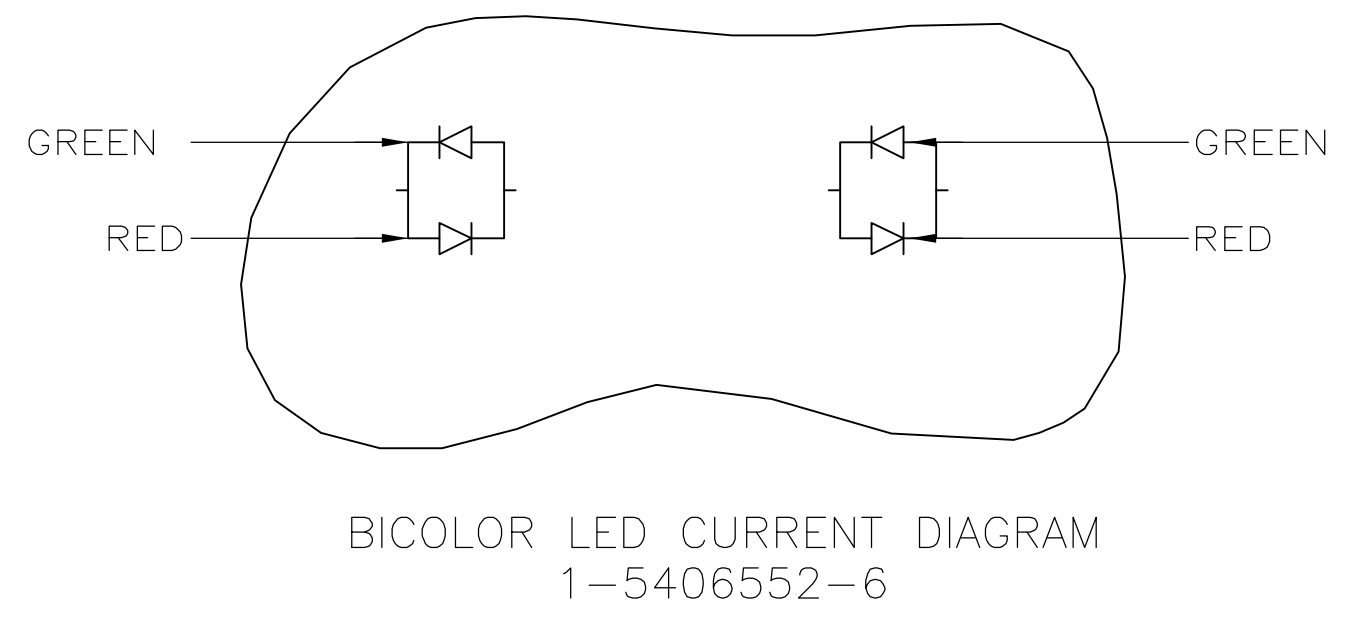
- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27μm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27μm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27μm[.000050] MINIMUM SATIN NICKEL WITH 2.03μm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μm THICK Sn/Cu OVER 2.03 μm THICK Ag OVER 1.02 μm THICK Cu OVER 3.56 μm THICK Ni OVER 1.02 μm THICK Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.

RED FOR 1-5406552-3
 YELLOW FOR 5406552-8
 ORANGE FOR 5406552-7



BI-COLOR LED CURRENT DIAGRAM

LED CURRENT DIAGRAM
5406552-9 ONLY

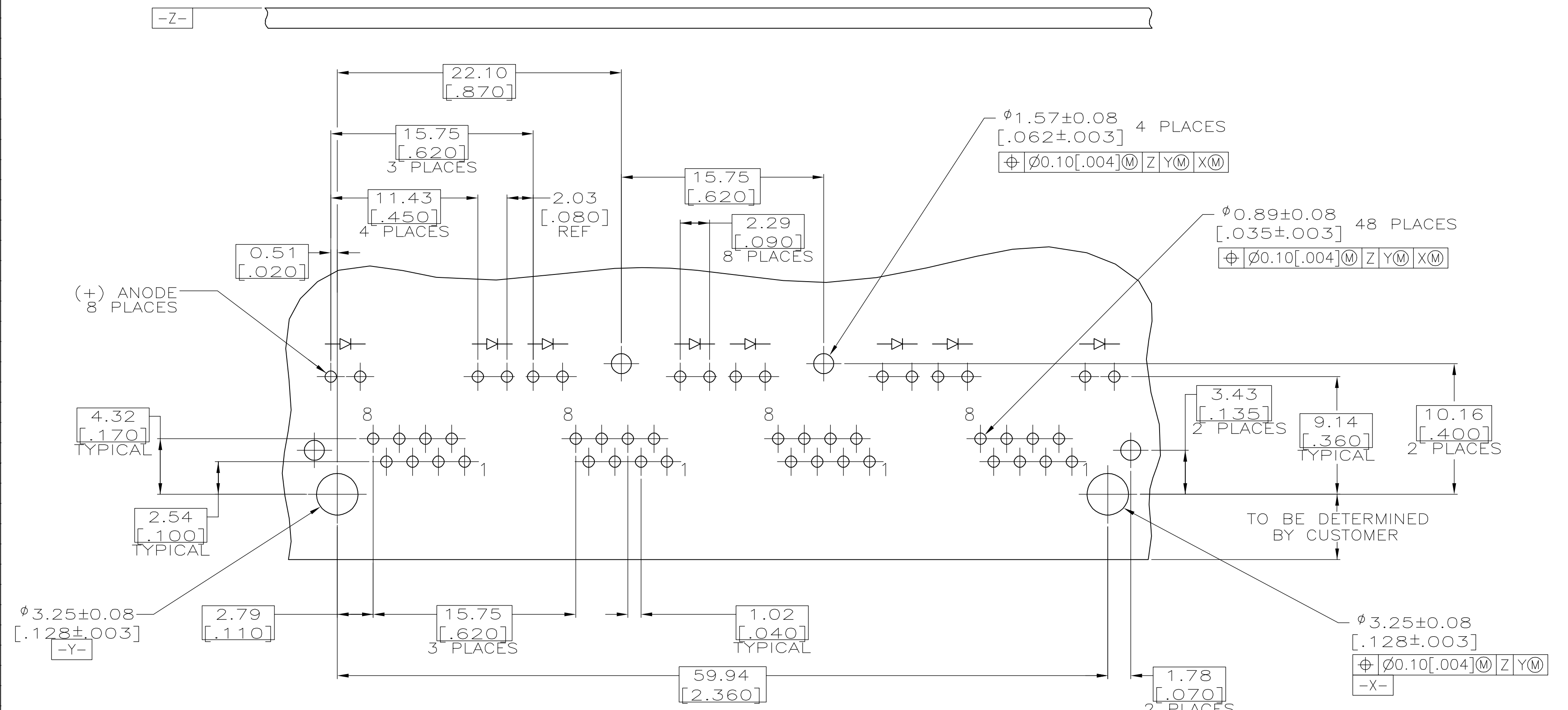


BICOLOR LED CURRENT DIAGRAM
1-5406552-6

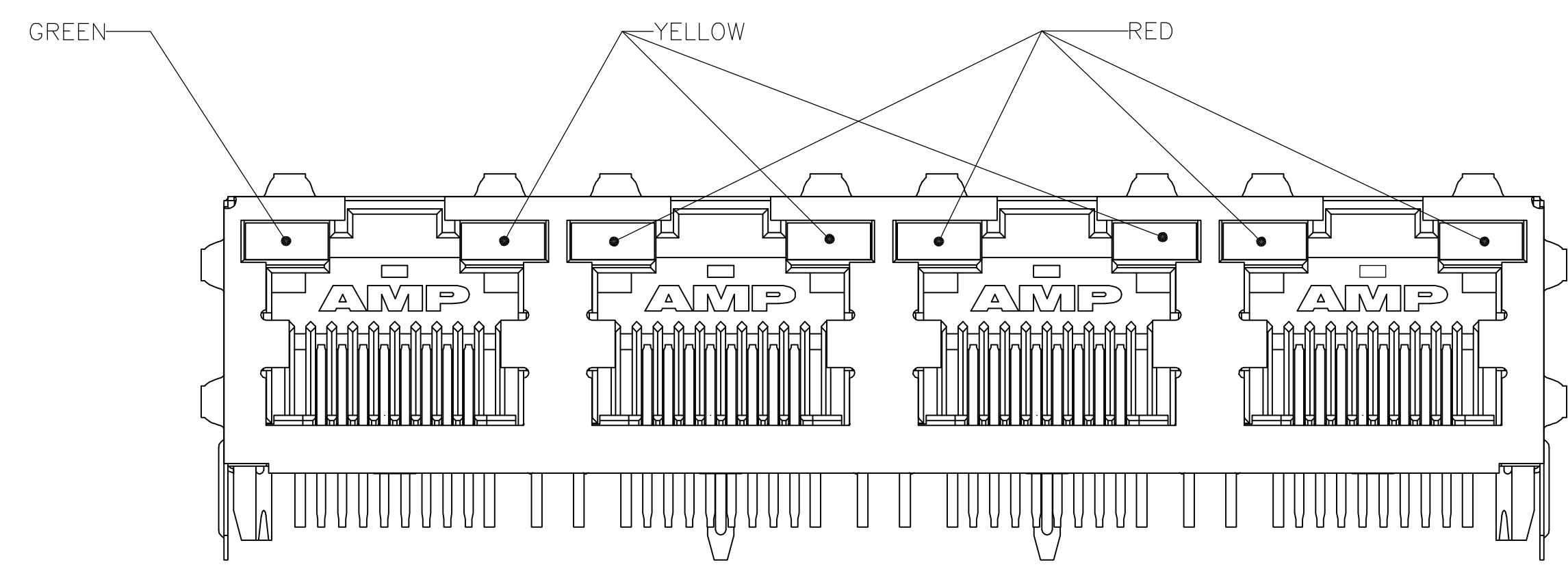
DIM A	POSITION 2	POSITION 1	PART NUMBER
.126	RED/GREEN	RED/GREEN	1-5406552-6
.100	SEE VIEW A (SHEET 2)	SEE VIEW A (SHEET 2)	1-5406552-5
.100	RED	GREEN	1-5406552-4
.100	GREEN/RED	GREEN/RED	1-5406552-3
.120	GREEN	GREEN	1-5406552-1
.100	GREEN/ORANGE	YELLOW	5406552-9
.100	GREEN/YELLOW	GREEN/YELLOW	5406552-8
.100	GREEN/ORANGE	GREEN/ORANGE	5406552-7
.100	YELLOW	YELLOW	5406552-6
.100	GREEN	GREEN	5406552-5
.100	GREEN	YELLOW	5406552-4
.100	YELLOW	-	5406552-3
.100	-	GREEN	5406552-2
.100	YELLOW	GREEN	5406552-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIM	T. SPRINKLE/L.A. MAYER	10MAY2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608
CHK	J. WESTMAN	10MAY2005	
APVD	S. FLICKINGER	10MAY2005	NAME
PRODUCT SPEC	INVERTED MODULAR JACK ASSEMBLY, 1X4, SHIELDED, PANEL GROUND, WITH LED		
APPLICATION SPEC	108-1163-4		
SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
114-2154		A100779	©=5406552
WEIGHT	CUSTOMER DRAWING		
SCALE	4:1	SHEET	1 OF 2



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)



VIEW A
 (1-5406552-5 ONLY)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. SPRINKLE/L.A. MAYER 10MAY2005		Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: mm		CHK J. WESTMAN 10MAY2005		APVD S. FLICKINGER 10MAY2005	NAME INVERTED MODULAR JACK ASSEMBLY, 1X4, SHIELDED, PANEL GROUND, WITH LED
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC 108-1163-4		APPLICATION SPEC 114-2154	SIZE A1
0 PLG ± -		100779		C=5406552	SCALE 4:1
1 PLG ± -		CUSTOMER DRAWING		WEIGHT	SHEET 2 OF 2
2 PLG ± 0.25(.01)				FINISH SEE NOTE 1	REV D
3 PLG ± 0.13(.005)					
4 PLG ± -					
ANGLES ± -					
MATERIAL SEE NOTE 1					